

Fabrication Parameters:

Number of layers:	2
Board name:	ldr.brd
Board width (dimension X):	140.000000 mm
Board length (dimension Y):	30.000000 mm
Board thickness:	1.570000 mm
Copper thickness outer layers:	0.035000 mm
Copper thickness inner layers:	undefined
Solder sides:	Both Sides
Silkscreen sides:	Top Side
Number of SMD pads on top:	0
Number of SMD pads on bottom:	0
Number of blind or buried hole types:	0
Minimum trace width (track width):	0.508000 mm
Minimum SMD pitch:	0.152400 mm
Minimum hole size:	1.016000 mm

Assembly Parameters:

Number of different packages:	2
Number of BGAs:	0
Number of QFNs:	0
Number of fine pitch packages:	0
Number of other SMDs:	0
Number of thru hole packages:	5
SMDs on both sides:	No